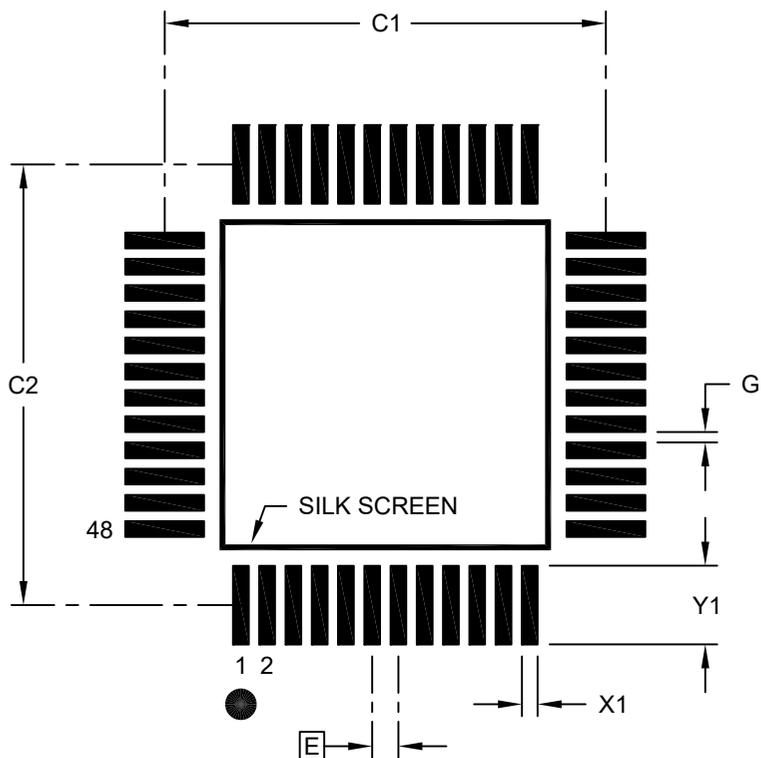


# 48-Lead Plastic Thin Quad Flatpack (Y8X) - 7x7x1.0 mm Body [TQFP]

**Note:** For the most current package drawings, please see the Microchip Packaging Specification located at <http://www.microchip.com/packaging>



## RECOMMENDED LAND PATTERN

		Units	MILLIMETERS		
Dimension Limits		MIN	NOM	MAX	
Contact Pitch	E	0.50 BSC			
Contact Pad Spacing	C1		8.40		
Contact Pad Spacing	C2		8.40		
Contact Pad Width (X48)	X1				0.30
Contact Pad Length (X48)	Y1				1.50
Distance Between Pads	G	0.20			

### Notes:

1. Dimensioning and tolerancing per ASME Y14.5M.  
BSC: Basic Dimension. The theoretically exact value is shown without tolerances.
2. For best soldering results, thermal vias, if used, should be filled or tented to avoid solder loss during the reflow process.